



Traditional High Q (>10,000) Low ESR
Multi-Layer Ceramic Capacitors

3838C/P (0.380" x 0.380")

≠ Product Features

- High Q
- High RF Current/Voltage
- Ultra Stable Performance
- Capacitance Range:
0.5pF to 5100pF
- Working Voltage: 3600V
- Extended Voltage: 7200V

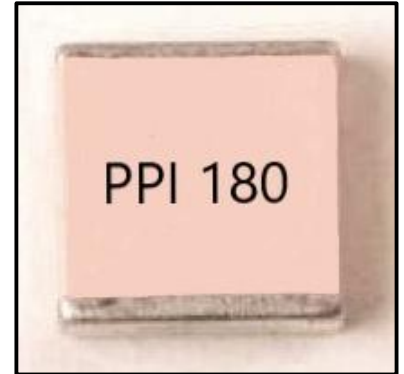
≠ Product Applications

Typical Functional Applications:

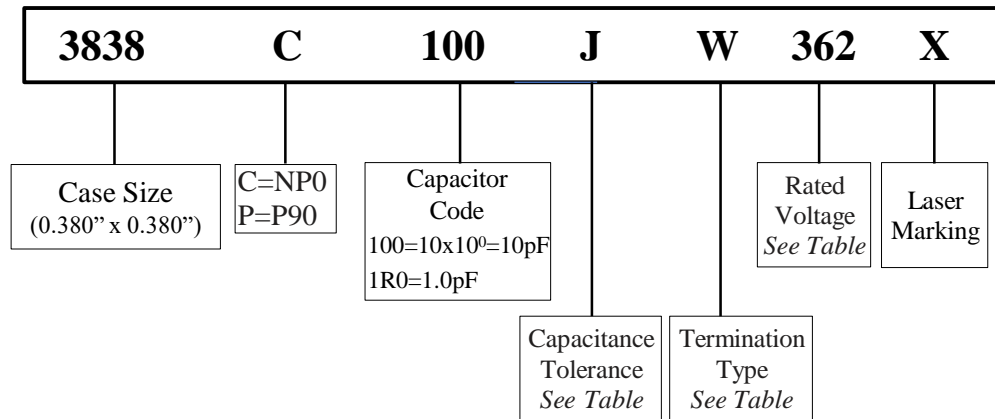
- Tuning • Bypass • Coupling
- D.C. Blocking • Impedance Matching

Typical Circuit Applications

- HF/ RF Power Amplifiers • Antenna Tuning • Plasma Chambers • Medical Equipment • Transmitters



≠ Part Numbering



≠ Capacitance Tolerance Codes

Code	A	B	C	D	F	G	J	K
Tol.	±0.05pF	±0.1pF	±0.25pF	±0.5pF	±1%	±2%	±5%	±10%

≠ Voltage Codes

Voltage	Code
500V	501
1000V	102
2500V	252
3600V	362
7200V	722



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≠ 3838C/P Capacitance Values

For special capacitances, tolerances and WVDC, please contact PPI.



			Rated WVDC					Rated WVDC					Rated WVDC	
Cap. pF	Code	Tol.	Std.	Ext.	Cap. pF	Code	Tol.	Std.	Ext.	Cap. pF	Code	Tol.		Rated WVDC
0.5	0R5				10	100				200	201			
0.6	0R6				11	110				220	221			
0.7	0R7				12	120				240	241			
0.8	0R8				13	130	B,C,D	3600V	7200V	270	271	F,G,J,K		3600V
0.9	0R9				15	150				300	301			
1.0	1R0				16	160				330	331			
1.1	1R1				18	180				360	361			
1.2	1R2				20	200				390	391			
1.3	1R3				22	220				430	431			
1.4	1R4				24	240				470	471			
1.5	1R5				27	270				510	511			
1.6	1R6				30	300				560	561	F,G,J,K		2500V
1.7	1R7				33	330				620	621			
1.8	1R8				36	360				680	681			
1.9	1R9				39	390				750	751			
2.0	2R0				43	430				820	821			
2.1	2R1	B,C,D	3600V	7200V	47	470				910	911			
2.2	2R2				51	510				1000	102			
2.4	2R4				56	560				1100	112			
2.7	2R7				62	620	F,G,J,K	3600V	7200V	1200	122	F,G,J,K		1000V
3.0	3R0				68	680				1500	152			
3.3	3R3				75	750				1800	182			
3.6	3R6				82	820				2200	222			
3.9	3R9				91	910				2400	242			
4.3	4R3				100	101				2700	272			
4.7	4R7				110	111				3000	302			
5.1	5R1				120	121				3300	332			
5.6	5R6				130	131				3600	362	F,G,J,K		500V
6.2	6R2				150	151				3900	392			
6.8	6R8				160	161				4300	432			
7.5	7R5				180	181				4700	472			
8.2	8R2									5100	512			
9.1	9R1													

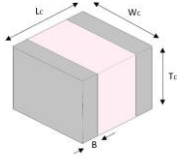




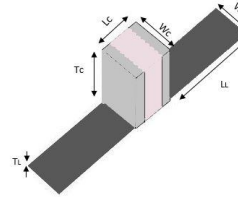
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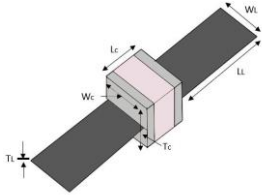
≠ Termination Types and Codes



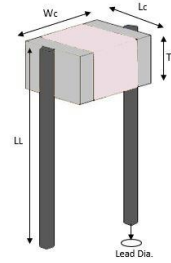
Chip Termination:
Codes: **W, L, P**



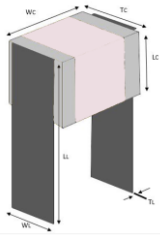
Microstrip Termination:
Codes: **MS, MN**



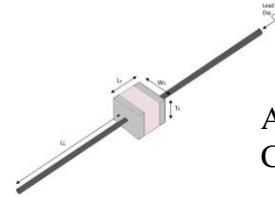
Axial Ribbon Termination:
Code: **AR, AN**



Radial Wire Termination:
Codes: **RW, RN**



Radial Ribbon Termination:
Code: **RR, FN**



Axial Wire Termination:
Codes: **AW, BN**

Termination Code	Magnetic Termination
W	100% Sn Solder over Nickel Plating
L	90% Sn10%Pb Tin/Lead Solder over Nickel Plating
MS	
AR	
RR	Silver-Plated Copper
RW	
AW	

Termination Code	Non-Magnetic Terminations
P	100%Sn Solder of Copper Plating
MN	
AN	
FN	Silver-Plated Copper
RN	
BN	

Note: "Non-Magnetic" means no magnetic materials.





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≠ Termination Types For Termination Types images, see previous page

Unit: inch (millimeter)

Magnetic Terminations								
Code	Term.	Capacitor Dimensions				Lead Dimensions		
		Length Lc	Width Wc	Thickness Tc	Overlap B	Length LL	Width WL	Thickness TL
W	Chip	0.380 -0.010+0.015 (9.65 - 0.25+0.38)	0.380 ±0.010 (9.65±0.25)	0.170 (4.32) max	0.024~0.059 (0.60~1.50)			
MS	Microstrip					0.728 (18.50) min	0.350 ± 0.020 (8.89±0.50)	0.008±0.001 (0.20±0.025)
AR	Axial Ribbon	0.380	0.380				0.315±0.010 (8.00±0.25)	
RR	Radial Ribbon	-0.010.+0.015	±0.010	0.177 (4.50) max		0.354 (9.00) min	0.118 ± 0.010 (3.0 ± 0.25)	0.012 ± 0.001 (0.3 ± 0.025)
RW	Radial Wire	(9.65 -0.25+0.38)	(9.65 ±0.25)			0.709 (18.00) min	Dia.: 0.031±0.004 (0.80 ± 0.10)	
AW	Axial Wire					0.906 (23.00) min		

⊗ Non-Magnetic Termination: ⊗								
Code	Term.	Capacitor Dimensions				Lead Dimensions		
		Length Lc	Width Wc	Thickness Tc	Overlap B	Length LL	Width WL	Thickness TL
P	Chip	0.380 -0.010+0.015 (9.65 - 0.25+0.38)	0.380 ±0.010 (9.65±0.25)	0.170 (4.32) max	0.024~0.059 (0.60~1.50)			
MN	Microstrip					0.728 (18.50) min	0.350 ± 0.020 (8.89±0.50)	0.008 ± 0.001 (0.20 ± 0.025)
AN	Axial Ribbon	0.380	0.380				0.315±0.010 (8.00±0.25)	
FN	Radial Ribbon	-0.010+0.015	±0.010	0.177 (4.50) max		0.354 (9.00) min	0.118 ± 0.010 (3.0 ± 0.25)	0.012 ± 0.001 (0.3 ± 0.025)
RN	Radial Wire	(9.65 -0.25+0.38)	(9.65 ±0.25)			0.709 (18.00) min	Dia.: 0.031 ± 0.004 (0.80 ± 0.10)	
BN	Axial Wire					0.906 (23.00) min		

Note: Non-Magnetic means no magnetic materials. All leads are attached with high temperature solder and parts are RoHS Compliant.





⚡ Electrical Specifications

Quality Factor (Q)	Greater than 10,000 at 1 MHz
Insulation Resistance (IR)	Test Voltage: 500V 10 ⁵ Megaohms min. @ +25°C rated WVDC 10 ⁴ Megaohms min. @ +125°C rated WVDC
Rated Voltage	See Rated Voltage Table
Dielectric Withstanding Voltage (WVDC)	250% of Rated Voltage of 5 seconds, Rated Voltage ≤ 500VDC 150% of Voltage for 5 seconds, 500VDC < Rated Voltage ≤ 1250 VDC 120% of Voltage for 5 seconds, Rated Voltage > 1250 VDC
Operating Temperature Range	-55°C to 200°C
Temperature Coefficient (TC)	C: -55°C to 125°C 0±30ppm/°C; >125°C to 200°C 0±60ppm/°C P: -55°C to 200°C +90±20ppm/°C
Capacitance Drift	±0.02% or ±0.02pF, whichever is greater
Piezoelectric Effects	None
Termination Type	See Termination Type Table

⚡ Environmental Specifications

	Specification	Test Parameters
Thermal Shock	DWV: The initial value IR: Shall not be less than 30% of the initial value. Capacitance Change:	MIL-STD-202, Method 107, Condition A. At the maximum rated temperature (-55°C and 200°C) stay 30 minutes, the time of removing shall not be more than 3 minutes. Perform five cycles.
Moisture Resistance	No more than 0.5% or 0.5pF, whichever is greater.	MIL-STD-202, Method 106
Humidity (Steady State)	DWV: The initial value IR: The initial value Capacitance Change: No more than 0.3% or 0.3pF, whichever is greater.	MIL-STD-202, Method 103, Condition A With 1.5Volts DC applied while subjected to an environment of 85°C with 85% relative humidity for 240 hours minimum.
Life	IR: Shall not be less than 30% of the initial value. Capacitance Change: No more than 2.0% or 0.5pF, whichever is greater.	MIL-STD-202, Method 108. For 2000 hours, at 200°C. 200% of Voltage for Capacitors, Rated Voltage ≤ 500VDC; 120% of Voltage for Capacitors, 500VDC < Rated Voltage ≤ 1250VDC; 100% for Voltage for Capacitors, Rated Voltage > 1250VDC
Terminal Strength	Force: 20lbs typical, 10lbs. min. Duration Time: 5 to 10 seconds	MIL-STD-202, Method 211A, Test Condition A. Applied a force and maintained for a period of 5 to 10 seconds. The force shall be in the direction of the axes of the terminations.

Capacitors are designed and manufactured to meet the requirements of MIL-PRF-55681 and MIL-PRF-123.

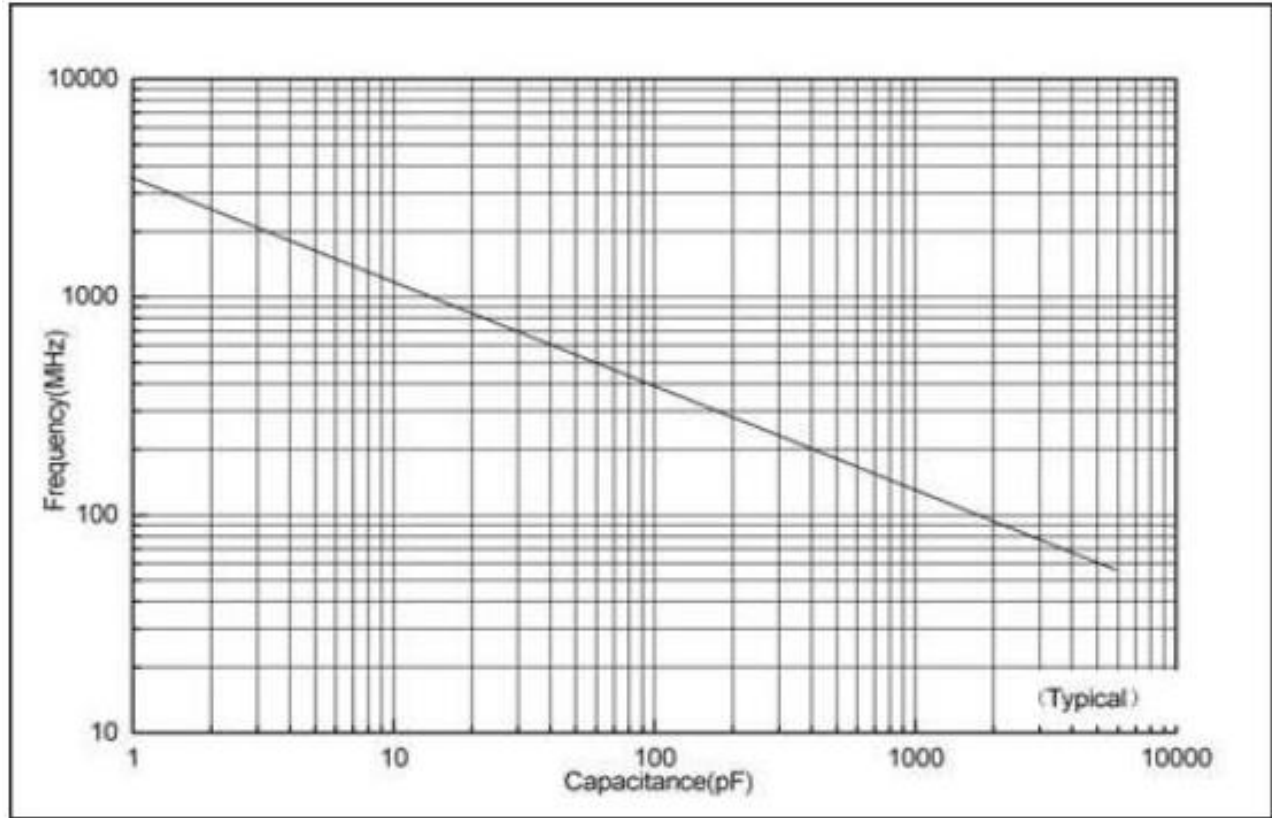


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≡ Series Resonance vs. Capacitance

Series Resonance vs. Capacitance



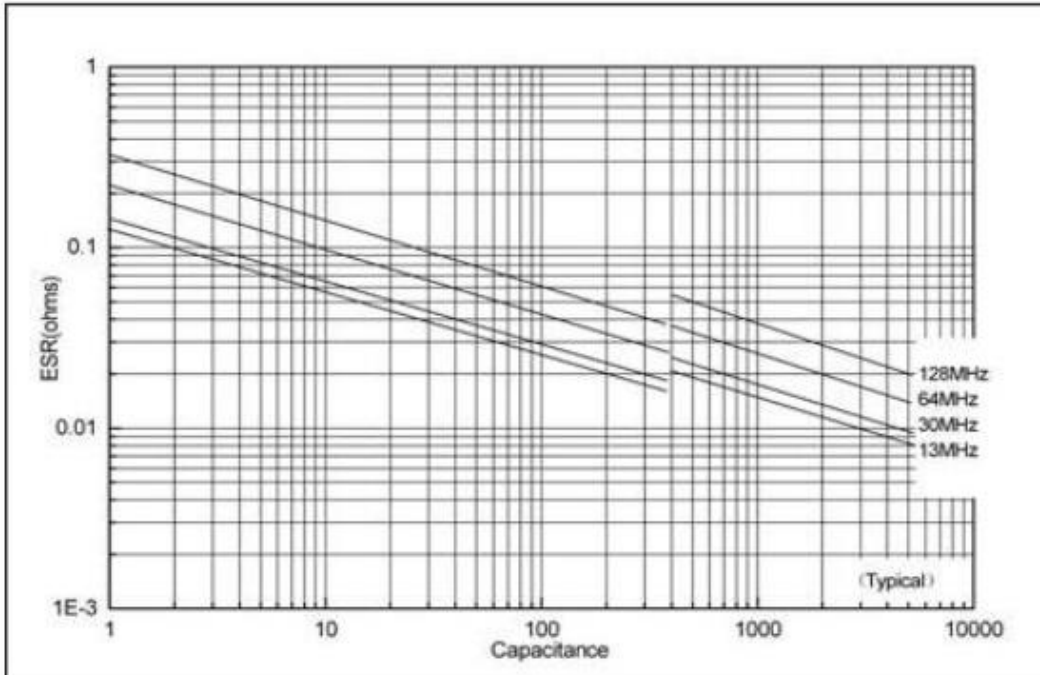


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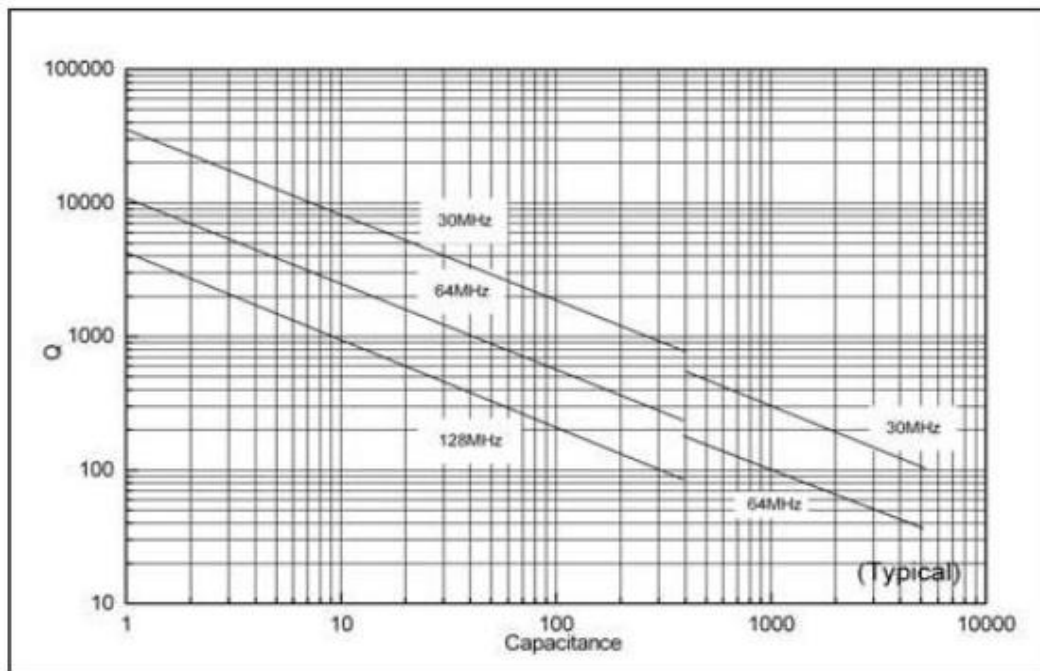
≠ ESR vs. Frequency

ESR vs Frequency



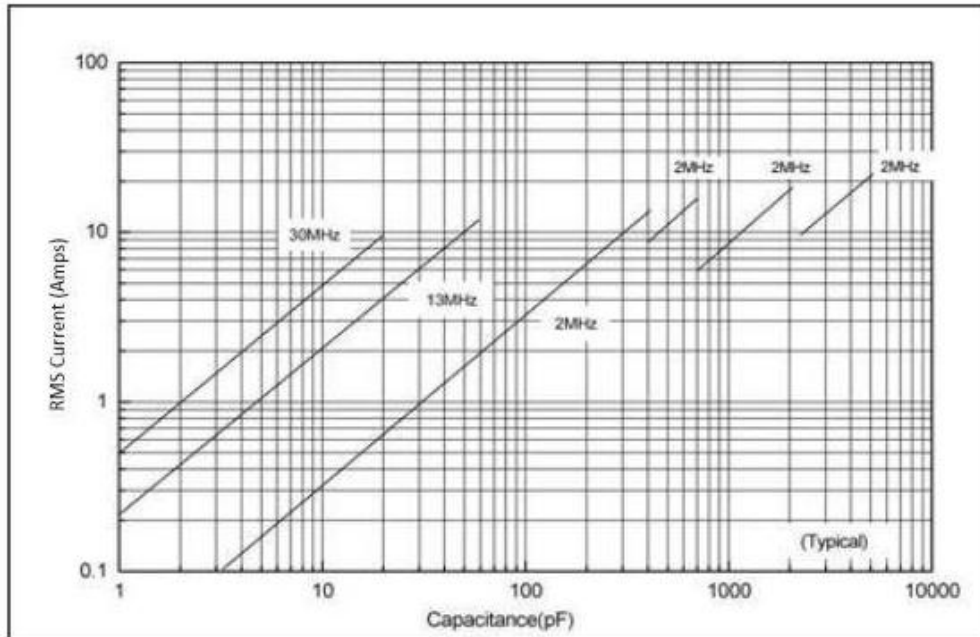
≠ Q vs. Capacitance

Q vs Capacitance



≠ Current Rating vs. Capacitance

3838C/P Current Rating vs Capacitance



The current depends on voltage limited:

$$I = \frac{\sqrt{2}}{2} I_{peak} = \frac{\sqrt{2}}{2} \times \frac{V_{rated}}{X_C} = \sqrt{2\pi f C V_{rated}}$$

The current depends on power dissipation limited:

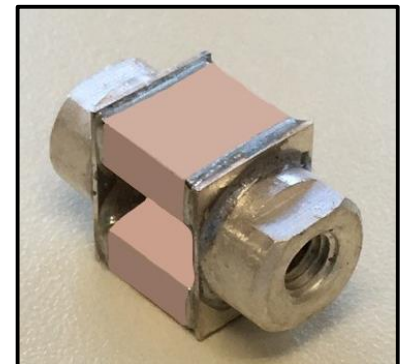
$$I = \sqrt{\frac{P_{dissipation}}{ESR}}$$

Note: If the thermal resistance of mounting surface is 12°C/W, then a power dissipation of 5W will result in the current limited. We can calculate the current limited.

≠ Custom Assemblies

Passive Plus offers Capacitor Assemblies for high power requirements. Typical assemblies are configured in series and/or parallel combinations, producing higher voltage/current handling capabilities, extended capacitance range and tighter tolerances.

To get started, simply send us either a mechanical drawing or circuit conditions and we can recommend a solution. All components are 100% up-screened for Partial Discharge and Sonoscanned. All assemblies include a 100hr Military burn in.



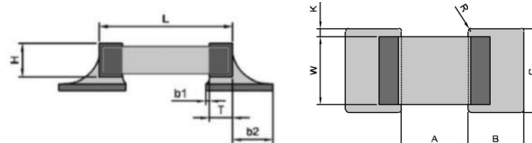
≠ Recommended Land Pattern Dimensions

When mounting the capacitor to substrate, it's important to carefully consider that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it's mounted.

- 1) The greater the amount of solder, the greater the stress to the elements. This may cause the substrate to break or crack.
- 2) In the situation where two or more devices are mounted onto a common land, be sure to separate the device into exclusive pads by using soldering resist.

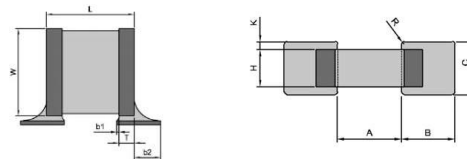
≠ Horizontal Mounting (mm)

A	B	C
7.1	3.0	10.2



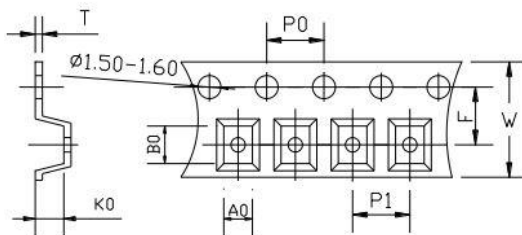
≠ Vertical Mounting* (mm)

A	B	C
7.1	3.0	5.0



≠ Tape & Reel Specifications (mm)

Horizontal Orientation



Orientation	W	P0	P1	T	F	Qty/Min	Qty/reel	Tape Material
Horizontal	16.00	4.00	12.00	0.30	7.50	50	200	Plastic

A₀ B₀ K₀

- Determined by component size. Typical clearance between the cavity and the component is:
.05 (.002) min to .50 (.020) max for 8mm tape and .50 (.002) min to .65 (.026) max for 12mm tape.
- The component cannot rotate more than 20° within the determined cavity.